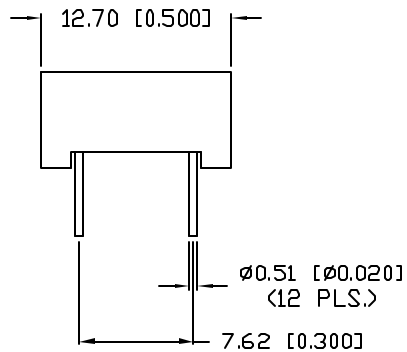
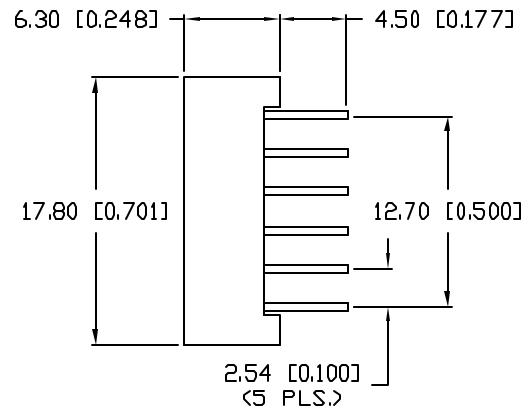
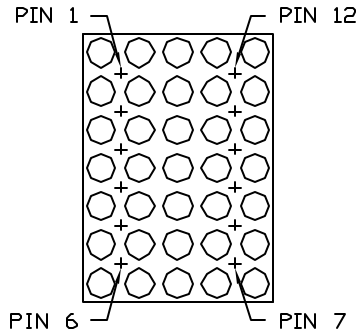


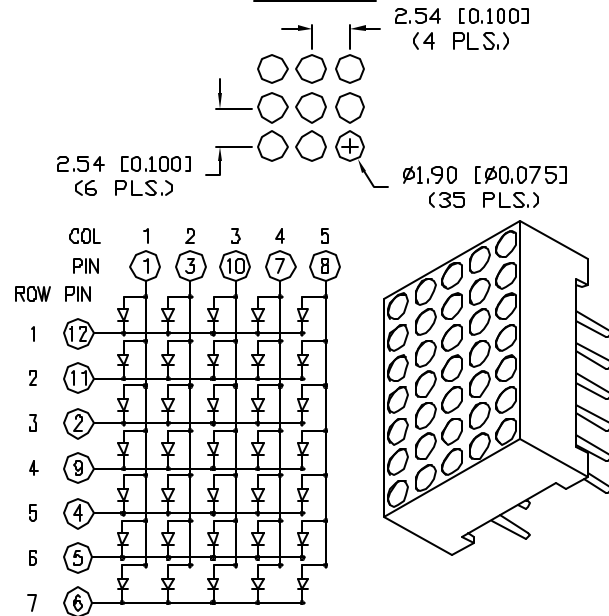
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PART NUMBER
LDM-07657MI

REV.
C



MATRIX DETAIL



COL	1	2	3	4	5
PIN	①	③	⑩	⑦	⑧
ROW	12	11	2	9	4
1	⑫	⑪	②	⑨	④
2	⑪	⑩	①	⑧	③
3	⑩	⑨	⑧	⑦	⑥
4	⑨	⑧	⑦	⑥	⑤
5	⑧	⑦	⑥	⑤	④
6	⑦	⑥	⑤	④	③
7	⑥	⑤	④	③	②

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR.	7.12.99
B	E.C.N. #10BRDR. & REDRAWN IN 3D.	6.28.03
C	E.C.N. #11148.	03.21.07

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.7	2.2	V_f	
REVERSE VOLTAGE	4.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		6000		μcd	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER DOT

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.6	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN=+0.00 DECIMAL PRECISION MAX=-0.00 DECIMAL PRECISION

REV. C	PART NUMBER LDM-07657MI
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0.70" 5 x 7 DOT MATRIX, LED DISPLAY,
660nm RED DOTS, GRAY FACE WITH WHITE SEGMENTS,
COLUMN ANODE, 12 PINS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC	CHECKED BY:	APPROVED BY:	DATE: 11.4.93
			PAGE: 1 OF 1
			SCALE: N/A

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